SMT-II
Low Static
Cleaning System
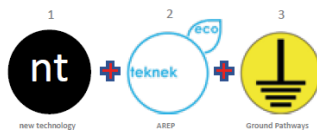# for Bare Boards

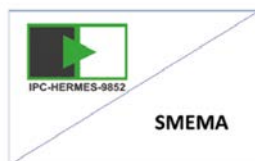# Resedue-free Cleaning
# of Bare Boards

SMT-II by Teknek creates a new benchmark in SMT board cleaning.

With Low Static Cleaning and Low Applied Pressure SMT-II provides the perfect method for removing contamination before solder paste print.
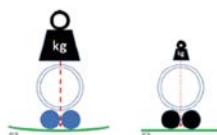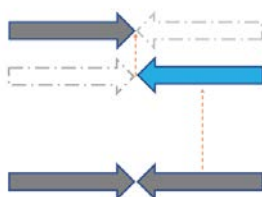
Industry demands for increased traceability and integration have been addressed, SMT-II comes with IPC Hermes as standard.

Features:

Low Static Cleaning

Benefits:

Every part of SMT-II has been designed to clean boards within a low static environment. This is achieved through careful design along with patented elastomer and adhesive technology

① NT™ Rollers ② Low Static Adhesive ③ Pathways

Network

Communication between equipment within the SMT process has never been more important, not only will the SMT-II fully integrate into the process but will also come as standard with IPC-Hermes-9852 or SMEMA capability.

Interface

With a new simple to use graphics user interface, SMT-II is easy to set up and run.

Low Applied Pressure

As technology drives the need for thinner and more complex boards, they can become more fragile. Applied pressure at any point in the assembly process may cause damage. SMT-II boasts the lowest applied pressure of any cleaner bringing high efficiency cleaning with no damage.

Follow-Me

An option on the new SMT-II is "Follow-Me". If your SMT process is not being controlled by Hermes, this independent auto width change system continually monitors the moving rail on the machine before or behind the SMT-II. During board change overs this feature removes the need for the operator to be involved increasing process up-time.

SMT-II Load Static Cleaning system – Technical Specification

Desription	
Two cleaning widths	40 – 400 mm 40 – 600 mm
Operation modes	Double side cleaning and bypass or single side cleaning and bypass
Elastomer rollers	NT™ or UTF-Nanoclean™
Adhesive rollers	AREP or AREF
Progressing speed	1-40 m/min.
Pass line height	900 +/-50 mm
Mains Power	85-265Vac
Pneumatic pressure	5-7 bar oil free compressed air
ESD compatibility	
Machine	ANSI / ESDs 6.1-2014 & IEC 61340-5-1 2016
All Rollers	ISO 6123 Class A
NT™/Nanocleen™ 20.20	ANSI / ESDs 20.20-2014
All Adhesives	FINAT

Usable board sizes and thicknesses

		SMT-II/400	**SMT-II/600**
Single side cleaning	Min - Max Length Min - Max Width Min - Max Thickness	50mm - N/A 40mm - 400mm 0.6mm - 3.2mm	50mm - N/A 40mm - 600mm 0.6mm - 3.2mm
Bypass without cleaning	Min - Max Length Min - Max Width Min - Max Thickness	50mm - N/A 40mm - 400mm 0.6mm - 3.2mm	50mm - N/A 40mm - 600mm 0.6mm - 3.2mm
Double side cleaning	Min - Max Length Min - Max Width Min - Max Thickness	98mm - N/A 40mm - 400mm 0.6mm - 3.2mm	98mm - N/A 40mm - 600mm 0.6mm - 3.2mm
Bypass without cleaning	Min - Max Length Min - Max Width Min - Max Thickness	120mm - N/A 40mm - 400mm 0.6mm - 3.2mm	120mm - N/A 40mm - 600mm 0.6mm - 3.2mm

Dimensions of SMT-II
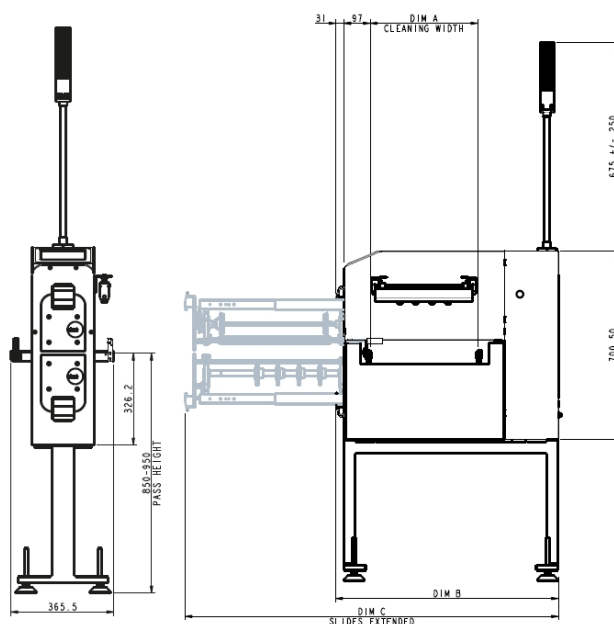
Machine width	Cleaning width	Overal width	Slides extended
	DIM A	DIM B	DIM C
SMT-II/400	400	828	1388
SMT-II/600	622	1078	1878

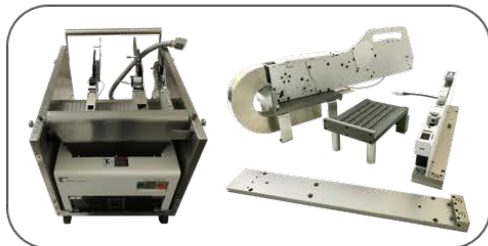# Our Product Portfolio
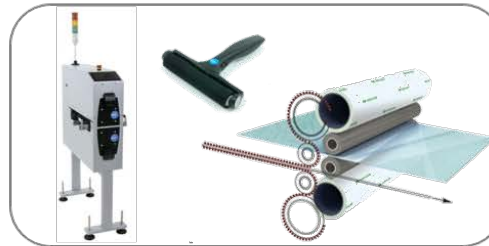

Feeding Technology

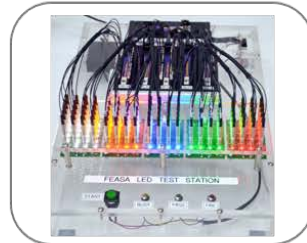Label Feeder, Labels and Marking Solutions

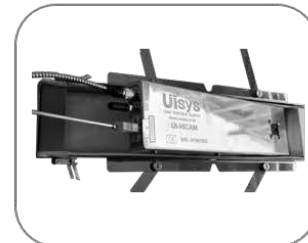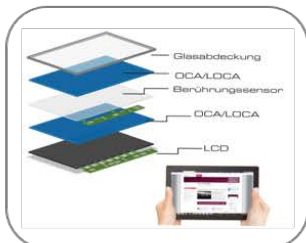
Special Applications
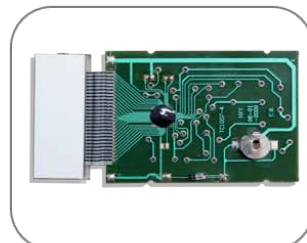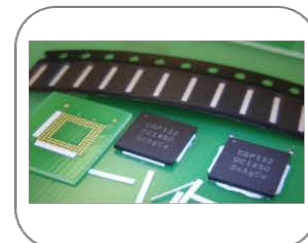

Bare Board Cleaning

In-System Programming

LED Analysis

Reflow Inline Camera

Optical Bonding

Thermal Bonding

Place-N-Bond

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